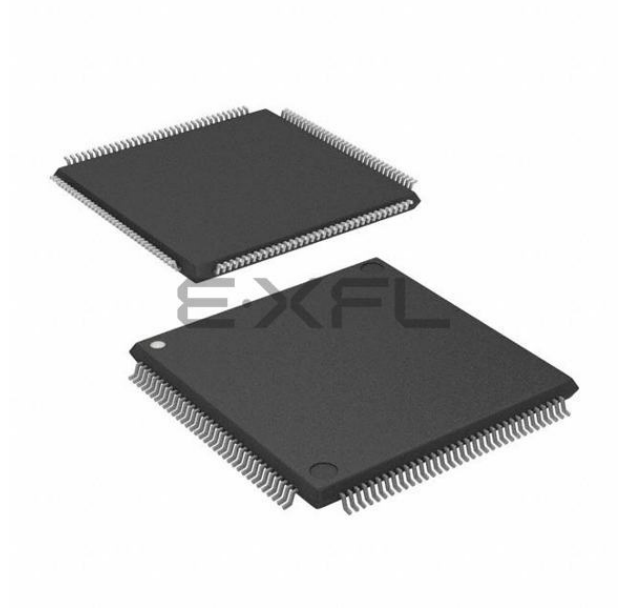

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	32-Bit Single-Core
Speed	66MHz
Connectivity	EBI/EMI, Ethernet, I²C, SPI, SSC, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	109
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at32uc3a0512-altta

1. Description

The AT32UC3A is a complete System-On-Chip microcontroller based on the AVR32 UC RISC processor running at frequencies up to 66 MHz. AVR32 UC is a high-performance 32-bit RISC microprocessor core, designed for cost-sensitive embedded applications, with particular emphasis on low power consumption, high code density and high performance.

The processor implements a Memory Protection Unit (MPU) and a fast and flexible interrupt controller for supporting modern operating systems and real-time operating systems. Higher computation capabilities are achievable using a rich set of DSP instructions.

The AT32UC3A incorporates on-chip Flash and SRAM memories for secure and fast access. For applications requiring additional memory, an external memory interface is provided on AT32UC3A0 derivatives.

The Peripheral Direct Memory Access controller (PDCA) enables data transfers between peripherals and memories without processor involvement. PDCA drastically reduces processing overhead when transferring continuous and large data streams between modules within the MCU.

The PowerManager improves design flexibility and security: the on-chip Brown-Out Detector monitors the power supply, the CPU runs from the on-chip RC oscillator or from one of external oscillator sources, a Real-Time Clock and its associated timer keeps track of the time.

The Timer/Counter includes three identical 16-bit timer/counter channels. Each channel can be independently programmed to perform frequency measurement, event counting, interval measurement, pulse generation, delay timing and pulse width modulation.

The PWM modules provides seven independent channels with many configuration options including polarity, edge alignment and waveform non overlap control. One PWM channel can trigger ADC conversions for more accurate close loop control implementations.

The AT32UC3A also features many communication interfaces for communication intensive applications. In addition to standard serial interfaces like UART, SPI or TWI, other interfaces like flexible Synchronous Serial Controller, USB and Ethernet MAC are available.

The Synchronous Serial Controller provides easy access to serial communication protocols and audio standards like I2S.

The Full-Speed USB 2.0 Device interface supports several USB Classes at the same time thanks to the rich End-Point configuration. The On-The-GO (OTG) Host interface allows device like a USB Flash disk or a USB printer to be directly connected to the processor.

The media-independent interface (MII) and reduced MII (RMII) 10/100 Ethernet MAC module provides on-chip solutions for network-connected devices.

AT32UC3A integrates a class 2+ Nexus 2.0 On-Chip Debug (OCD) System, with non-intrusive real-time trace, full-speed read/write memory access in addition to basic runtime control.

5. Signals Description

The following table gives details on the signal name classified by peripheral

The signals are multiplexed with GPIO pins as described in ”Peripheral Multiplexing on I/O lines” on page 31.

Table 5-1. Signal Description List

Signal Name	Function	Type	Active Level	Comments
Power				
VDDPLL	Power supply for PLL	Power Input		1.65V to 1.95 V
VDDCORE	Core Power Supply	Power Input		1.65V to 1.95 V
VDDIO	I/O Power Supply	Power Input		3.0V to 3.6V
VDDANA	Analog Power Supply	Power Input		3.0V to 3.6V
VDDIN	Voltage Regulator Input Supply	Power Input		3.0V to 3.6V
VDDOUT	Voltage Regulator Output	Power Output		1.65V to 1.95 V
GNDANA	Analog Ground	Ground		
GND	Ground	Ground		
Clocks, Oscillators, and PLL’s				
XIN0, XIN1, XIN32	Crystal 0, 1, 32 Input	Analog		
XOUT0, XOUT1, XOUT32	Crystal 0, 1, 32 Output	Analog		
JTAG				
TCK	Test Clock	Input		
TDI	Test Data In	Input		
TDO	Test Data Out	Output		
TMS	Test Mode Select	Input		
Auxiliary Port - AUX				
MCKO	Trace Data Output Clock	Output		
MDO0 - MDO5	Trace Data Output	Output		

Table 5-1. Signal Description List

Signal Name	Function	Type	Active Level	Comments
External Bus Interface - HEBI				
ADDR0 - ADDR23	Address Bus	Output		
CAS	Column Signal	Output	Low	
DATA0 - DATA15	Data Bus	I/O		
NCS0 - NCS3	Chip Select	Output	Low	
NRD	Read Signal	Output	Low	
NWAIT	External Wait Signal	Input	Low	
NWE0	Write Enable 0	Output	Low	
NWE1	Write Enable 1	Output	Low	
NWE3	Write Enable 3	Output	Low	
RAS	Row Signal	Output	Low	
SDA10	SDRAM Address 10 Line	Output		
SDCK	SDRAM Clock	Output		
SDCKE	SDRAM Clock Enable	Output		
SDCS0	SDRAM Chip Select	Output	Low	
SDWE	SDRAM Write Enable	Output	Low	
General Purpose Input/Output 2 - GPIOA, GPIOB, GPIOC				
P0 - P31	Parallel I/O Controller GPIOA	I/O		
P0 - P31	Parallel I/O Controller GPIOB	I/O		
P0 - P5	Parallel I/O Controller GPIOC	I/O		
P0 - P31	Parallel I/O Controller GPIOX	I/O		
Serial Peripheral Interface - SPI0, SPI1				
MISO	Master In Slave Out	I/O		
MOSI	Master Out Slave In	I/O		
NPCS0 - NPCS3	SPI Peripheral Chip Select	I/O	Low	
SCK	Clock	Output		
Synchronous Serial Controller - SSC				
RX_CLOCK	SSC Receive Clock	I/O		

6. Package and Pinout

The device pins are multiplexed with peripheral functions as described in ”Peripheral Multiplexing on I/O lines” on page 31.

Figure 6-1. TQFP100 Pinout

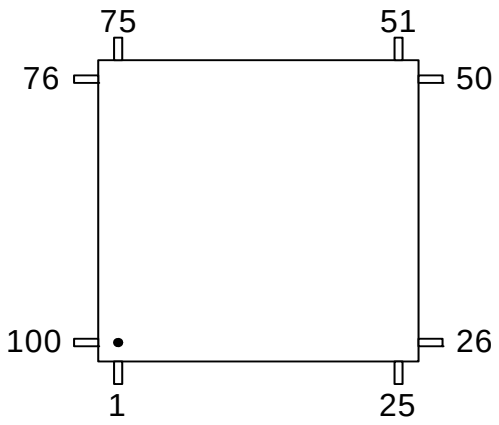


Table 6-1. TQFP100 Package Pinout

1	PB20	**26**	PA05	**51**	PA21	**76**	PB08
2	PB21	**27**	PA06	**52**	PA22	**77**	PB09
3	PB22	**28**	PA07	**53**	PA23	**78**	PB10
4	VDDIO	**29**	PA08	**54**	PA24	**79**	VDDIO
5	GND	**30**	PA09	**55**	PA25	**80**	GND
6	PB23	**31**	PA10	**56**	PA26	**81**	PB11
7	PB24	**32**	N/C	**57**	PA27	**82**	PB12
8	PB25	**33**	PA11	**58**	PA28	**83**	PA29
9	PB26	**34**	VDDCORE	**59**	VDDANA	**84**	PA30
10	PB27	**35**	GND	**60**	ADVREF	**85**	PC02
11	VDDOUT	**36**	PA12	**61**	GNDANA	**86**	PC03
12	VDDIN	**37**	PA13	**62**	VDDPLL	**87**	PB13
13	GND	**38**	VDDCORE	**63**	PC00	**88**	PB14
14	PB28	**39**	PA14	**64**	PC01	**89**	TMS
15	PB29	**40**	PA15	**65**	PB00	**90**	TCK
16	PB30	**41**	PA16	**66**	PB01	**91**	TDO
17	PB31	**42**	PA17	**67**	VDDIO	**92**	TDI
18	RESET_N	**43**	PA18	**68**	VDDIO	**93**	PC04
19	PA00	**44**	PA19	**69**	GND	**94**	PC05
20	PA01	**45**	PA20	**70**	PB02	**95**	PB15
21	GND	**46**	VBUS	**71**	PB03	**96**	PB16
22	VDDCORE	**47**	VDDIO	**72**	PB04	**97**	VDDCORE

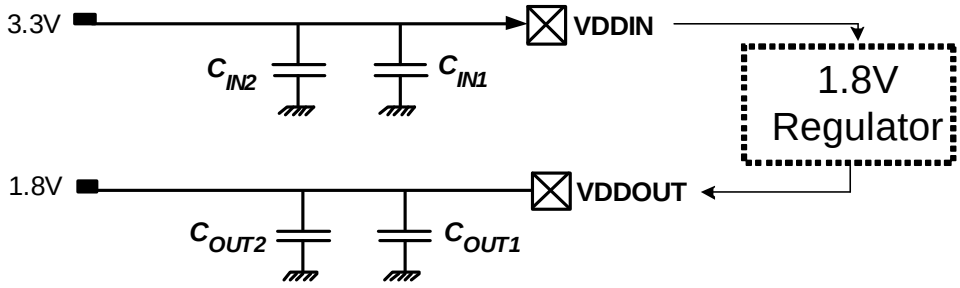
7.2 Voltage Regulator

7.2.1 Single Power Supply

The AT32UC3A embeds a voltage regulator that converts from 3.3V to 1.8V. The regulator takes its input voltage from VDDIN, and supplies the output voltage on VDDOUT. VDDOUT should be externally connected to the 1.8V domains.

Adequate input supply decoupling is mandatory for VDDIN in order to improve startup stability and reduce source voltage drop. Two input decoupling capacitors must be placed close to the chip.

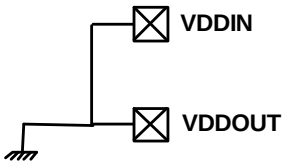
Adequate output supply decoupling is mandatory for VDDOUT to reduce ripple and avoid oscillations. The best way to achieve this is to use two capacitors in parallel between VDDOUT and GND as close to the chip as possible



Refer to Section 12.3 on page 42 for decoupling capacitors values and regulator characteristics

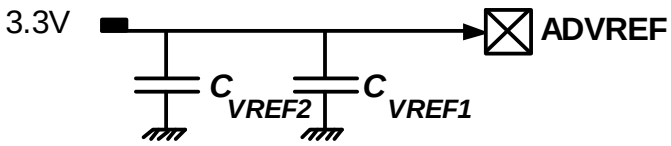
7.2.2 Dual Power Supply

In case of dual power supply, VDDIN and VDDOUT should be connected to ground to prevent from leakage current.



7.3 Analog-to-Digital Converter (A.D.C) reference.

The ADC reference (ADVREF) must be provided from an external source. Two decoupling capacitors must be used to insure proper decoupling.



Refer to Section 12.4 on page 42 for decoupling capacitors values and electrical characteristics.

In case ADC is not used, the ADVREF pin should be connected to GND to avoid extra consumption.

Table 10-1. Peripheral Address Mapping (Continued)

Address		Peripheral Name	Bus
0xFFFF1C00	USART2	Universal Synchronous Asynchronous Receiver Transmitter - USART2	PBA
0xFFFF2000	USART3	Universal Synchronous Asynchronous Receiver Transmitter - USART3	PBA
0xFFFF2400	SPI0	Serial Peripheral Interface - SPI0	PBA
0xFFFF2800	SPI1	Serial Peripheral Interface - SPI1	PBA
0xFFFF2C00	TWI	Two Wire Interface - TWI	PBA
0xFFFF3000	PWM	Pulse Width Modulation Controller - PWM	PBA
0xFFFF3400	SSC	Synchronous Serial Controller - SSC	PBA
0xFFFF3800	TC	Timer/Counter - TC	PBA
0xFFFF3C00	ADC	Analog To Digital Converter - ADC	PBA

10.2 CPU Local Bus Mapping

Some of the registers in the GPIO module are mapped onto the CPU local bus, in addition to being mapped on the Peripheral Bus. These registers can therefore be reached both by accesses on the Peripheral Bus, and by accesses on the local bus.

Mapping these registers on the local bus allows cycle-deterministic toggling of GPIO pins since the CPU and GPIO are the only modules connected to this bus. Also, since the local bus runs at CPU speed, one write or read operation can be performed per clock cycle to the local bus-mapped GPIO registers.

10.4.3 SPIs

Each SPI can be connected to an internally divided clock:

Table 10-6. SPI clock connections

SPI	Source	Name	Connection
0	Internal	CLK_DIV	PBA clock or PBA clock / 32
1			

10.5 Nexus OCD AUX port connections

If the OCD trace system is enabled, the trace system will take control over a number of pins, irrespectively of the PIO configuration. Two different OCD trace pin mappings are possible, depending on the configuration of the OCD AXS register. For details, see the AVR32 UC Technical Reference Manual.

Table 10-7. Nexus OCD AUX port connections

Pin	AXS=0	AXS=1
EVTI_N	PB19	PA08
MDO[5]	PB16	PA27
MDO[4]	PB14	PA26
MDO[3]	PB13	PA25
MDO[2]	PB12	PA24
MDO[1]	PB11	PA23
MDO[0]	PB10	PA22
EVTO_N	PB20	PB20
MCKO	PB21	PA21
MSEO[1]	PB04	PA07
MSEO[0]	PB17	PA28

10.6 PDC handshake signals

The PDC and the peripheral modules communicate through a set of handshake signals. The following table defines the valid settings for the Peripheral Identifier (PID) in the PDC Peripheral Select Register (PSR).

Table 10-8. PDC Handshake Signals

PID Value	Peripheral module & direction
0	ADC
1	SSC - RX
2	USART0 - RX
3	USART1 - RX

10.10 GPIO

The GPIO open drain feature (GPIO ODMER register (Open Drain Mode Enable Register)) is not available for this device.

10.11 Peripheral overview

10.11.1 External Bus Interface

- **Optimized for Application Memory Space support**
- **Integrates Two External Memory Controllers:**
  - **Static Memory Controller**
  - **SDRAM Controller**
- **Optimized External Bus:**
  - **16-bit Data Bus**
  - **24-bit Address Bus, Up to 16-Mbytes Addressable**
  - **Optimized pin multiplexing to reduce latencies on External Memories**
- **4 SRAM Chip Selects, 1SDRAM Chip Select:**
  - **Static Memory Controller on NCS0**
  - **SDRAM Controller or Static Memory Controller on NCS1**
  - **Static Memory Controller on NCS2**
  - **Static Memory Controller on NCS3**

10.11.2 Static Memory Controller

- **4 Chip Selects Available**
- **64-Mbyte Address Space per Chip Select**
- **8-, 16-bit Data Bus**
- **Word, Halfword, Byte Transfers**
- **Byte Write or Byte Select Lines**
- **Programmable Setup, Pulse And Hold Time for Read Signals per Chip Select**
- **Programmable Setup, Pulse And Hold Time for Write Signals per Chip Select**
- **Programmable Data Float Time per Chip Select**
- **Compliant with LCD Module**
- **External Wait Request**
- **Automatic Switch to Slow Clock Mode**
- **Asynchronous Read in Page Mode Supported: Page Size Ranges from 4 to 32 Bytes**

10.11.3 SDRAM Controller

- **Numerous Configurations Supported**
  - **2K, 4K, 8K Row Address Memory Parts**
  - **SDRAM with Two or Four Internal Banks**
  - **SDRAM with 16-bit Data Path**
- **Programming Facilities**
  - **Word, Half-word, Byte Access**
  - **Automatic Page Break When Memory Boundary Has Been Reached**
  - **Multibank Ping-pong Access**
  - **Timing Parameters Specified by Software**
  - **Automatic Refresh Operation, Refresh Rate is Programmable**
- **Energy-saving Capabilities**
  - **Self-refresh, Power-down and Deep Power Modes Supported**

12.3 Regulator characteristics

Table 12-2. Electrical characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{VDDIN}	Supply voltage (input)		3	3.3	3.6	V
V_{VDDOUT}	Supply voltage (output)		1.81	1.85	1.89	V
I_{OUT}	Maximum DC output current with $V_{VDDIN = 3.3V}$				100	mA
	Maximum DC output current with $V_{VDDIN = 2.7V}$				90	mA
I_{SCR}	Static Current of internal regulator	Low Power mode (stop, deep stop or static) at T_A =25°C		10		µA

Table 12-3. Decoupling requirements

Symbol	Parameter	Condition	Typ.	Techno.	Units
C_{IN1}	Input Regulator Capacitor 1		1	NPO	nF
C_{IN2}	Input Regulator Capacitor 2		4.7	X7R	uF
C_{OUT1}	Output Regulator Capacitor 1		470	NPO	pF
C_{OUT2}	Output Regulator Capacitor 2		2.2	X7R	uF

12.4 Analog characteristics

Table 12-4. Electrical characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{ADVREF}	Analog voltage reference (input)		2.6		3.6	V

Table 12-5. Decoupling requirements

Symbol	Parameter	Condition	Typ.	Techno.	Units
C_{VREF1}	Voltage reference Capacitor 1		10	-	nF
C_{VREF2}	Voltage reference Capacitor 2		1	-	uF

12.4.1 BOD

Table 12-6. BODLEVEL Values

BODLEVEL Value	Typ.	Typ.	Typ.	Units.
00 0000b	1.40	1.47	1.55	V
01 0111b	1.45	1.52	1.6	V
01 1111b	1.55	1.6	1.65	V
10 0111b	1.65	1.69	1.75	V

The values in Table 12-6 describes the values of the BODLEVEL in the flash FGPFR register.

12.7.2 Main Oscillators Characteristics

Table 12-15. Main Oscillator Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$1/(t_{CPMAIN})$	Crystal Oscillator Frequency		0.45		16	MHz
C_{L1}, C_{L2}	Internal Load Capacitance ($C_{L1} = C_{L2}$)			12		pF
	Duty Cycle		40	50	60	%
t_{ST}	Startup Time				TBD	ms
$1/(t_{CPXIN})$	XIN Clock Frequency	External clock			50	MHz
		Crystal	0.45		16	MHz
t_{CHXIN}	XIN Clock High Half-period		0.4 x t_{CPXIN}		0.6 x t_{CPXIN}	
t_{CLXIN}	XIN Clock Low Half-period		0.4 x t_{CPXIN}		0.6 x t_{CPXIN}	
C_{IN}	XIN Input Capacitance			7		pF

12.7.3 PLL Characteristics

Table 12-16. Phase Lock Loop Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
F_{OUT}	Output Frequency		80		240	MHz
F_{IN}	Input Frequency		4		16	MHz
I_{PLL}	Current Consumption	active mode (Fout=80Mhz)		250		µA
		active mode (Fout=240Mhz)		600		µA

12.8 ADC Characteristics

Table 12-17. Channel Conversion Time and ADC Clock

Parameter	Conditions	Min	Typ	Max	Units
ADC Clock Frequency	10-bit resolution mode			5	MHz
ADC Clock Frequency	8-bit resolution mode			8	MHz
Startup Time	Return from Idle Mode			20	µs
Track and Hold Acquisition Time		600			ns
Conversion Time	ADC Clock = 5 MHz			2	µs
Conversion Time	ADC Clock = 8 MHz			1.25	µs
Throughput Rate	ADC Clock = 5 MHz			384(1)	kSPS
Throughput Rate	ADC Clock = 8 MHz			533(2)	kSPS

Notes: 1. Corresponds to 13 clock cycles at 5 MHz: 3 clock cycles for track and hold acquisition time and 10 clock cycles for conversion.

2. Corresponds to 15 clock cycles at 8 MHz: 5 clock cycles for track and hold acquisition time and 10 clock cycles for conversion.

Table 12-18. External Voltage Reference Input

Parameter	Conditions	Min	Typ	Max	Units
ADVREF Input Voltage Range		2.6		VDDANA	V
ADVREF Average Current	On 13 samples with ADC Clock = 5 MHz		200	250	µA
Current Consumption on VDDANA				1.25	mA

Note: ADVREF should be connected to GND to avoid extra consumption in case ADC is not used.

Table 12-19. Analog Inputs

Parameter	Min	Typ	Max	Units
Input Voltage Range	0		V_{ADVREF}	
Input Leakage Current			1	µA
Input Capacitance		17		pF

Table 12-20. Transfer Characteristics in 8-bit mode

Parameter	Conditions	Min	Typ	Max	Units
Resolution			8		Bit
Absolute Accuracy	f=5MHz			0.8	LSB
	f=8MHz			1.5	LSB
Integral Non-linearity	f=5MHz		0.35	0.5	LSB
	f=8MHz		0.5	1.0	LSB
Differential Non-linearity	f=5MHz		0.3	0.5	LSB
	f=8MHz		0.5	1.0	LSB
Offset Error	f=5MHz	-0.5		0.5	LSB
Gain Error	f=5MHz	-0.5		0.5	LSB

Table 12-24. SMC Read Signals with no Hold Settings

Symbol	Parameter	Min	Units
NRD Controlled (READ_MODE = 1)			
SMC_{19}	Data Setup before NRD High	13.7	ns
SMC_{20}	Data Hold after NRD High	1	
NRD Controlled (READ_MODE = 0)			
SMC_{21}	Data Setup before NCS High	13.3	ns
SMC_{22}	Data Hold after NCS High	0	

Table 12-25. SMC Write Signals with Hold Settings

Symbol	Parameter	Min	Units
NRD Controlled (READ_MODE = 1)			
SMC_{23}	Data Out Valid before NWE High	(nwe pulse length - 1) * t_{CPSMC} - 0.9	ns
SMC_{24}	Data Out Valid after NWE High(1)	nwe hold length * t_{CPSMC} - 6	
SMC_{25}	NWE High to NBS0/A0 Change(1)	nwe hold length * t_{CPSMC} - 1.9	
SMC_{26}	NWE High to NBS1 Change(1)	nwe hold length * t_{CPSMC} - 1.9	
SMC_{29}	NWE High to NBS2/A1 Change(1)	nwe hold length * t_{CPSMC} - 1.9	
SMC_{30}	NWE High to NBS3 Change(1)	nwe hold length * t_{CPSMC} - 1.9	
SMC_{31}	NWE High to A2 - A25 Change(1)	nwe hold length * t_{CPSMC} - 1.7	
SMC_{32}	NWE High to NCS Inactive(1)	(nwe hold length - ncs wr hold length)* t_{CPSMC} - 2.9	
SMC_{33}	NWE Pulse Width	nwe pulse length * t_{CPSMC} - 0.9	
NRD Controlled (READ_MODE = 0)			
SMC_{34}	Data Out Valid before NCS High	(ncs wr pulse length - 1)* t_{CPSMC} - 4.6	ns
SMC_{35}	Data Out Valid after NCS High(1)	ncs wr hold length * t_{CPSMC} - 5.8	
SMC_{36}	NCS High to NWE Inactive(1)	(ncs wr hold length - nwe hold length)* t_{CPSMC} - 0.6	

Note: 1. hold length = total cycle duration - setup duration - pulse duration. “hold length” is for “ncs wr hold length” or “nwe hold length"

Figure 12-4. SDRAMC Signals relative to SDCK.

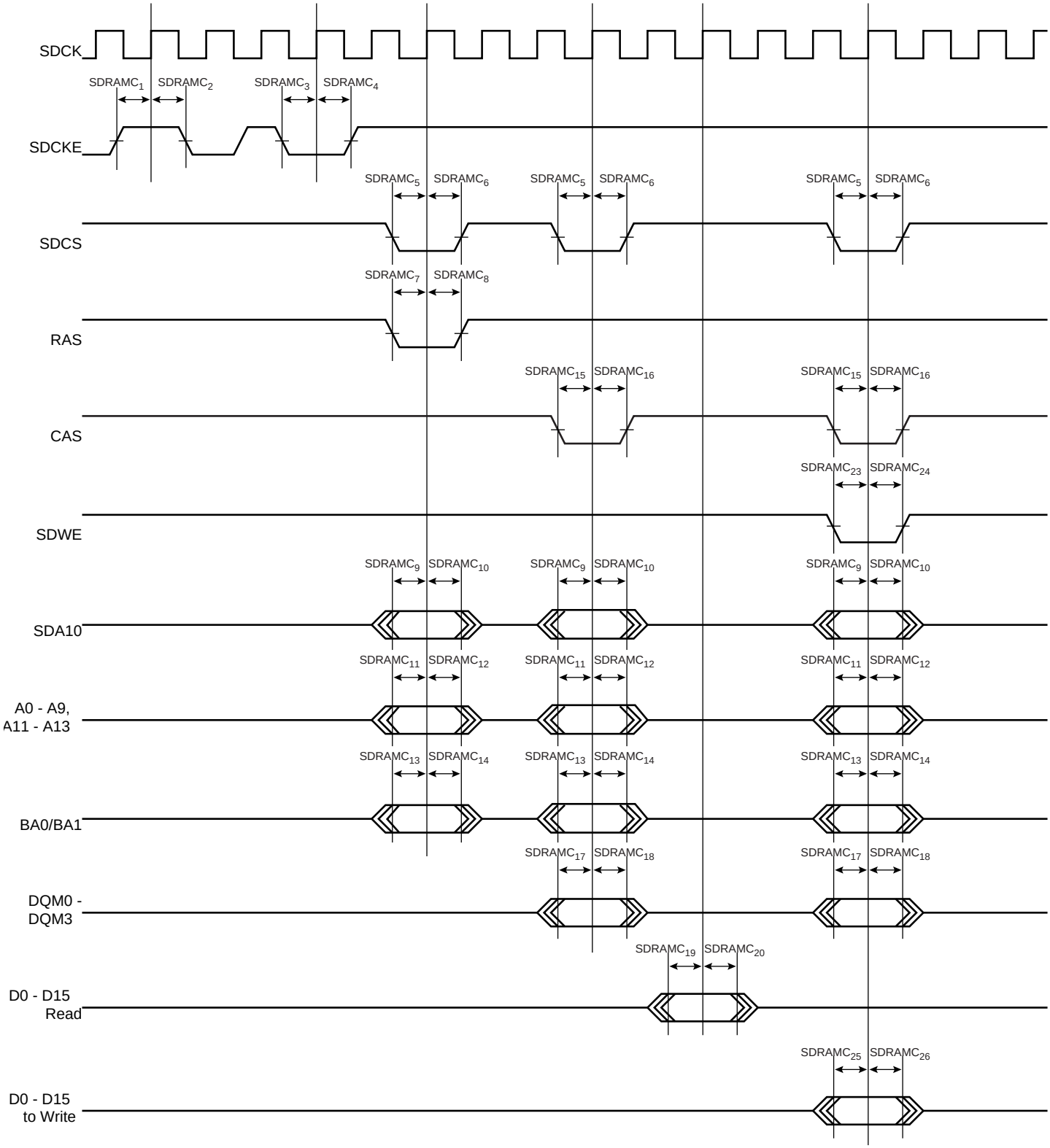
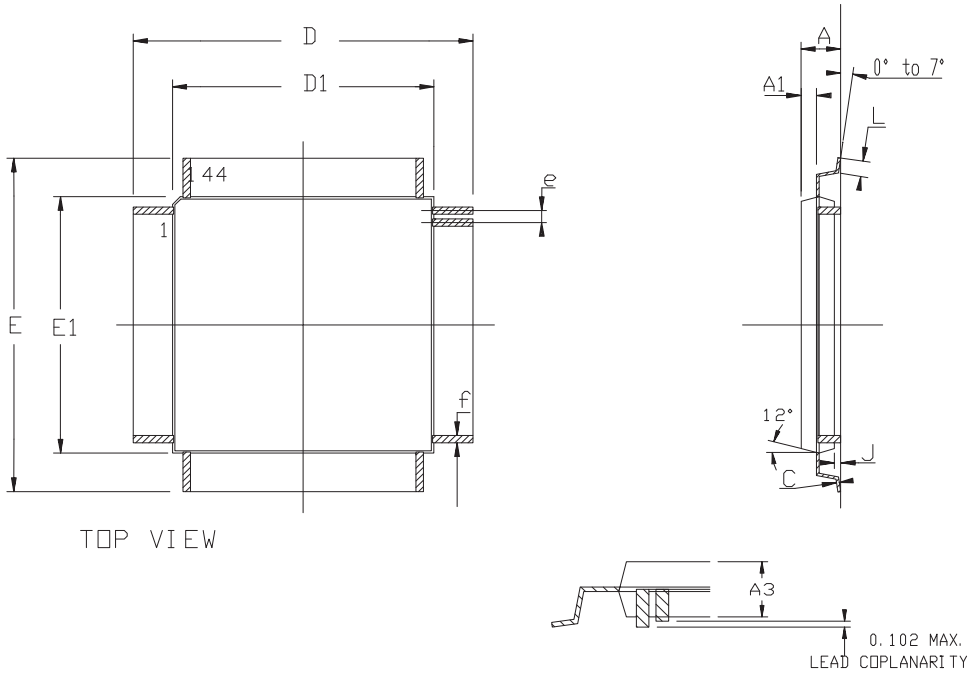


Figure 13-2. LQFP-144 package drawing



	MM		INCH	
	Min	Max	Min	Max
A	–	1.60	–	.063
C	0.09	0.20	.004	.008
A3	1.35	1.45	.053	.057
D	21.90	22.10	.862	.870
D1	19.90	20.10	.783	.791
E	21.90	22.10	.862	.870
E1	19.90	20.10	.783	.791
J	0.05	0.15	.002	.006
L	0.45	0.75	.018	.030
e	0.50 BSC		.0197 BSC	
f	0.22 BSC		.009 BSC	

Table 13-5. Device and Package Maximum Weight

1300	mg

Table 13-6. Package Characteristics

Moisture Sensitivity Level	Jdec J-STD0-20D - MSL 3

Table 13-7. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

13.3 Soldering Profile

Table 13-11 gives the recommended soldering profile from J-STD-20.

Table 13-11. Soldering Profile

Profile Feature	Green Package
Average Ramp-up Rate (217°C to Peak)	3°C/sec
Preheat Temperature 175°C ±25°C	Min. 150 °C, Max. 200 °C
Time Maintained Above 217°C	60-150 sec
Time within 5·C of Actual Peak Temperature	30 sec
Peak Temperature Range	260 °C
Ramp-down Rate	6 °C/sec
Time 25·C to Peak Temperature	Max. 8 minutes

Note: It is recommended to apply a soldering temperature higher than 250°C.

A maximum of three reflow passes is allowed per component.

None.

15.2.9 USART

1. **ISO7816 info register US_NER cannot be read**
   The NER register always returns zero.
   Fix/Workaround
   None

15.2.10 Processor and Architecture

1. **LDM instruction with PC in the register list and without ++ increments Rp**
   For LDM with PC in the register list: the instruction behaves as if the ++ field is always set, ie the pointer is always updated. This happens even if the ++ field is cleared. Specifically, the increment of the pointer is done in parallel with the testing of R12.
   Fix/Workaround
   None.

2. **RETE instruction does not clear SREG[L] from interrupts.**
   The RETE instruction clears SREG[L] as expected from exceptions.
   Fix/Workaround
   When using the STCOND instruction, clear SREG[L] in the stacked value of SR before returning from interrupts with RETE.

3. **Exceptions when system stack is protected by MPU**
   RETS behaves incorrectly when MPU is enabled and MPU is configured so that system stack is not readable in unprivileged mode.
   Fix/Woraround
   Workaround 1: Make system stack readable in unprivileged mode,
   or
   Workaround 2: Return from supervisor mode using rete instead of rets. This requires :
   1. Changing the mode bits from 001b to 110b before issuing the instruction. Updating the mode bits to the desired value must be done using a single mtsr instruction so it is done atomically. Even if this step is described in general as not safe in the UC technical reference guide, it is safe in this very specific case.
   2. Execute the RETE instruction.

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2. Execute the RETE instruction.

16. Datasheet Revision History

Please note that the referring page numbers in this section are referred to this document. The referring revision in this section are referring to the document revision.

16.1 Rev. K – 01/12

1. Update "Errata" on page 70.
2. Update eletrical characteristic in "DC Characteristics" on page 41.
3. Remove Preliminary from first page.

16.2 Rev. G – 01/09

1. Update "Errata" on page 70.
2. Update GPIO eletrical characteristic in "DC Characteristics" on page 41.

16.3 Rev. F – 08/08

1. Add revision J to "Errata" on page 70.
2. Update DMIPS number in "Features" on page 1.

16.4 Rev. E – 04/08

1. Open Drain Mode removed from "General-Purpose Input/Output Controller (GPIO)" on page 151.

16.5 Rev. D – 04/08

1. Updated "Signal Description List" on page 8. Removed RXDN and TXDN from USART section.
2. Updated "Errata" on page 70. Rev G replaced by rev H.